Best Presentation Award

Room temperature bonding of Cr:LiSAF and sapphire: interface analysis and thermal properties

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Best Presentation Award

Xenon vs Argon Ion Activation for Room-Temperature Wafer Bonding of Si and SiC

P. Kerepesi[1,2], M. Danner[1], T. Wernicke[1] and H. Groiss[2]

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Best Poster Presentation Award

Effect of Temperature Ramping Rate on Thermal Expansion of Nanocrystalline Cu pads in Fine-Pitch SiO2 Vias for 3D IC Hybrid Bonding

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